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**COMSOL Conference 2013—Call for Papers**

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*The 9th Annual Conference on Multiphysics Simulation is Now Accepting Abstracts*

BURLINGTON, MA (March 19, 2013) – The Program Committee for the 9th annual COMSOL Conference on multiphysics simulation is pleased to invite engineers and researchers from around the globe to begin submitting abstracts describing their designs, projects and achievements for presentation at the Conference. Selected papers will be given the coveted opportunity to present their work at the world’s largest conference on multiphysics simulation and computer aided engineering.

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| **Conference Locations**  [Boston, MA: October 9 -11](http://www.comsol.com/conference2013/usa)  [Beijing, China: October 17](http://comsol2013.cntech.com.cn/)  [Bangalore, India: October 17 -18](http://www.comsol.com/conference2013/india/)  [Shanghai, China: October 24](http://comsol2013.cntech.com.cn/)  [Rotterdam, Netherlands: October 23 -25](http://www.comsol.com/conference2013/europe/) | Singapore, Singapore: October 24 -25  [Taipei, Taiwan: October 25](http://www.pitotech.com.tw/show_party.php?pid=8&id=1127)  [Seoul, Korea: November 15](http://www.altsoft.co.kr/web/conference2013_notice.php)  [Tokyo, Japan: December 6](http://www.kesco.co.jp/conference/2013/index.html) |

The COMSOL Conference connects more th­an 2,000 engineers, researchers and scientists worldwide, providing them with the chance to showcase their work, share innovative technologies and best practices, as well as with the opportunity to meet with the makers of COMSOL Multiphysics. The Conference focuses on advancing cross-discipline and multiphysics simulation by providing Conference attendees with a multitude of hands-on minicourses, networking opportunities, keynote talks from industry leaders and over 850 user presentations.

**Highlights of the Conference Include**

* Multiphysics minicourse sessions taught by COMSOL specialists that cover a wide array of disciplines and topics including electrical, mechanical, fluid and chemical applications.
* Keynote speeches from industry leaders and prominent researchers which in the past have included the Toyota Research Institute, Ford Motor Company, Robert Bosch GmbH, DuPont Company, Microsoft Corporation and others.
* Opportunities to interact with a panel of industry experts on multiphysics simulation and listen in on discussions surrounding real-world design challenges.
* An exhibition showcasing the services and products offered by COMSOL Partners and Certified Consultants to enhance and enrich your simulation experience.
* The announcement of a new version of COMSOL Multiphysics. Be the first to hear about new tools and technologies added to the COMSOL Multiphysics product suite.

Presenting a poster, paper, or both at the COMSOL Conference is an unparalleled and esteemed opportunity for multiphysics users to achieve widespread recognition within a highly skilled community of engineers and researchers. “It’s a great opportunity for attendees to connect with each other, share their work, and interact with experts of the same field,” says Dr. Jinlan Huang, Program Committee Chair of the Boston Conference. Not only will users who present at the Conference have the opportunity to showcase their work to fellow attendees, additionally papers and posters presented at the Conference will be published on the COMSOL website and get international recognition. You can see the contributions from 2012 by visiting the [COMSOL Conference User Presentations](http://www.comsol.com/offers/conference2012papers/) section of the website.

You are invited to be a part of this prestigious event by presenting your own work as an oral or poster presentation. Suggested topic areas include:

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| * AC/DC Electromagnetics * Acoustics and Vibrations * Batteries, Fuel Cells, and   Electrochemical Processes   * Bioscience and Bioengineering * Chemical Reaction Engineering * Computational Fluid Dynamics * Electromagnetic Heating * Geophysics and Geomechanics * Heat Transfer and Phase Change * MEMS and Nanotechnology * Microfluidics | * Multiphysics * Optics, Photonics and Semiconductors * Optimization and Inverse Methods * Particle Tracing * Piezoelectric Devices * Plasma Physics * RF and Microwave Engineering * Simulation Methods and Teaching * Structural Mechanics and   Thermal Stresses   * Transport Phenomena |

The Poster Session is one of the key events at the Conference. “What makes the Poster Session such a valuable part of the conference experience is the wide array of different applications that are presented,” says Bernt Nilsson, Sr. Vice President of Marketing at COMSOL, Inc. “With the Poster Session, not only do you have the opportunity to showcase your project during the scheduled session, but your work is also featured for the full three days of the Conference, allowing for ongoing discussions between the author and Conference attendees.”

**Call for Papers and Abstract Submission**

Abstract submissions will be reviewed by a Program Committee of 20 leaders in multiphysics simulation. This year, the Program Committee comprises an impressive assembly of scientists and researchers from renowned universities, governmental agencies and businesses including Harvard University, Pepsico, GE, and IBM.

To submit an abstract for review by the Program Committee, visit the [Call for Papers](http://www.comsol.com/conference2013/usa/papers/) page on the COMSOL website and select the Conference city you prefer. For the Boston Conference presenters who submit an abstract by the June 21 Early Bird Deadline, a discounted Conference registration fee will be provided. The final submission deadline for abstracts is August 2.

***About COMSOL***

COMSOL provides simulation software for product design and research to technical enterprises, research labs, and universities through over 17 offices and a distributor network all over the world.

Its flagship product, COMSOL Multiphysics®, is a software environment for modeling and simulating any physics-based system. A particular strength is its ability to account for coupled or multiphysics phenomena. Add-on products expand the simulation platform for electrical, mechanical, fluid flow, and chemical applications. Interfacing tools enable the integration of COMSOL Multiphysics simulation with all major technical computing and CAD tools on the CAE market.

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